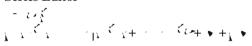
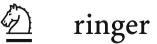


Series Editor



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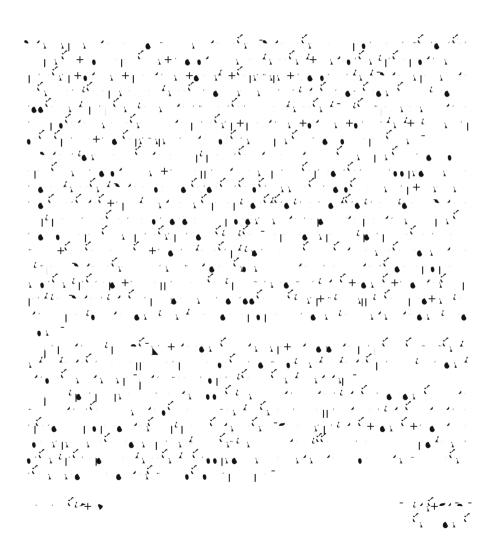
 $\begin{array}{c} x = \left[-x + \frac{1}{2} + \frac{1}{2}$

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Contributors

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 $\zeta_{\chi^{\mu}\ell} \subset \zeta$

D.G. Yang :
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